	Material Compo © Copyright 2005. If international and Pan	PC, Bannockb	ourn, Illinois. A	All rights reserved untions.	nder both	This docume level parts, th	ent is a declaration	tion of the	ne substances asses all low	s within the er level mat	manufactur erials for wl	er listed it hich the m	em. Note: it anufacturer	f the item is an as has engineering	sembly with low responsibility.
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					eous Materia	als and Mf	g Informati	on		
upplie	r Information														
Company name* Company				any unique ID			Unique ID Authority					Response Date*			
nsemi												2025-06-06			
ontact N	lame		Title - Contact			]	Phone - Contact*					Email - Contact*			
Product-l	Env-Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
uthorize	ed Representative*		Title - Representative			]	Phone - Representative*				Email - Representative*				
roduct-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item Number   FCP165N65S3R0		n Number Mfr Item Name				Effective Date	e Vers	ion	Manufacturing Site		V	Veight*	UOM	Unit Type
			N65S3R0	SUPERFET3 650V TO220 PKG			2025-06-06 CNC		ZNC		2	033.34	mg	Each	
Ianufa	cturing Proccess Informat	tion													
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 MS		L Rating	Peak Process Body Temperat		ure Max Time at Peak Temp		Temperatu	ire Numb	er of Reflow Cyc	eles		
Matte Tin (Sn) - annealed		C	CU Alloy NA			0 C		30		second	is 3				
omments	3														
or more	information regarding material	composition	please refer t	o page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless	otherwise noted).							
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	7.1	mg	Supplier	Silicon (Si)	7440-21-3		7.1	mg
Die Attach Solder	4.93	mg	Supplier	Silver (Ag)	7440-22-4		0.1233	mg
			А	Lead (Pb)	7439-92-1	7a	4.5602	mg
			Supplier	Tin (Sn)	7440-31-5		0.2465	mg
Lead Frame	1492.12	mg	В	Nickel (Ni)	7440-02-0		1.0445	mg
			Supplier	Iron (Fe)	7439-89-6		1.4921	mg
			Supplier	Copper (Cu)	7440-50-8		1489.1357	mg
			Supplier	Phosphorus (P)	7723-14-0		0.4476	mg
Mold Compound-Black	513.45	mg		Epoxy resin	proprietary data		30.807	mg
			Supplier	Phenolic Resin	Proprietary Data		30.807	mg
			Supplier	Carbon Black (C)	1333-86-4		2.5673	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		436.4325	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		12.8363	mg
Plating	13.3	mg	Supplier	Tin (Sn)	7440-31-5		13.3	mg
Wire Bond - Al	2.44	mg	Supplier	Aluminum (Al)	7429-90-5		2.44	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 signa range of distribution unless otherwise noted).